



MIL-PRF-31032

PRINTED BOARD CERTIFICATION

IS HEREBY AWARDED TO

**GORILLA CIRCUITS
1445 Old Oakland Road
San Jose, CA 95112**

THIS CERTIFICATION IS VALID UNTIL TERMINATED BY WRITTEN NOTIFICATION FROM DLA LAND AND MARITIME. REFERENCE DLA LAND AND MARITIME LETTER VQ(VQE-10-020866) FOR DETAILS PERTAINING TO THIS CERTIFICATION.

SAMUEL E. MERRITT
Director, Operations Support Directorate
DLA Land and Maritime



DEFENSE LOGISTICS AGENCY

LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

April 14, 2011

Mr. David Williams
Gorilla Circuits
1445 Old Oakland Rd
San Jose CA 95112

Dear Mr. Williams:

Re: Notification of Qualification, MIL-PRF-31032; FSC 5998; CAGE Code 3C7D2; VQE-11-022314

Qualification of products is granted as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification sheets MIL-PRF-31032/1 and /2. The capabilities qualified for each base material and specification sheet indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is April 8, 2011.

MANUFACTURER INFORMATION	BASIC PLANT LOCATION	PHONE: (408) 294-9897 FAX: (408) 297-1540 EMAIL: info@gorillacircuits.com CAGE CODE: 3C7D2
Gorilla Circuits 1445 Old Oakland Rd San Jose CA 95112	Same	
CAPABILITIES BY TECHNOLOGY / PRINTED BOARD TYPE: MIL-PRF-31032 /1, /2		
Base Materials	GF (Woven E-Glass, Epoxy Resin)	
Qualification Letters	VQE-11-022314	
Max. Panel Size	18" X 24"	
Number of Layers	18	
Max. Board Thickness	0.180"	
Min. Plated Thru Hole (before plating)	0.010"	
Aspect Ratio (plated through hole)	18:1	
Min. Conductor Width	0.004"	
Min. Conductor Spacing	0.005"	
Hole Preparation	Permanganate Desmear, Plasma Desmear	
Hole Wall Conductive Coating	Electroless Copper	
Copper Plating Method	Periodic Reverse Plate	
Solder Resist	LPI	
Finish System	HASL, ENIG, Electrolytic Nickel/Hard Gold	
Controlled Impedance	Single-Ended, Differential	

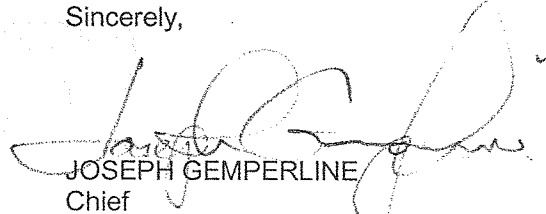
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Test report number 31032-3217-11 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this Office immediately if a failure occurs during PCI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. If you have any questions, please contact Mr. Jonathan Stone, (614) 692-0625 or vqe.js@dla.mil.

Sincerely,



JOSEPH GEMPERLINE
Chief
Sourcing and Qualification Division

Visit us on the web at www.dsccl.dla.mil/offices/sourcing_and_qualification